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## **TECHNICAL DATA SHEET 667**

Page 1 of 1

# *No***SWEEP**<sup>™</sup> *Wire Bond Encapsulant EW8002*

### **DESCRIPTION**

Polysciences, Inc. Low Viscosity thermal only *NoSWEEP™* Wire Bond Encapsulant is a novel, 100% solids, one component, silica filled liquid encapsulant designed for quick self leveling, in large Dam and Fill applications, easy dispensing at lower temperatures including RT, and encapsulation of very narrow diameter, long and ultra fine pitch wire bonds on semiconductor devices. *NoSWEEP™* can be dispensed onto the wires immediately after wire bonding, flowing easily between and around the wires without causing sweep or sag and without voids.

## **CUSTOMER BENEFITS**

**NoSWEEP™** Liquid Encapsulant offers the following distinct advantages over conventional molding systems:

- Enables implementation of 35µm pitch roadmap wire bonding
- Enhanced stress management through the ability to achieve low modulus for a given CTE
- Allows for the use of longer wires with low cost, high-density substrates and enable simple die shrinks
- Enables cost reduction through the use of thinner diameter gold wire
- Fast flow and self leveling properties for large Dam and fill applications
- Excellent adhesion to both inorganic and organic substrates

## **UNCURED (WET) PROPERTIES**

Color Black

Filler Content Filler avg size/max 6/30 microns

Viscosity @ 25°C RVDV-II+, Spindle 14, Cup 6R

50 kcps @ 0.5 rpm

Pot Life @ 25° C

>24 hours

**Density** 

1.7 gram/cm<sup>3</sup>

#### **PROCESS PARAMETERS**

**Cure Cycle** 

60 min. @ 100°C + 60 min. @ 165°C

**Alternate Cure Cycle** 

30 min. @ 100°C + 120 min. @ 150°C

#### **CURED PROPERTIES**

Glass Transition Temp. (Tg) by DMA

150°C

**Coefficient of Thermal Expansion (CTE)** 

15 ppm/°C

**Flexural Modulus (Three Point Bend)** 

2.0 GPa @ 25°C

**Extractable Ionic Content** 

CI<10 K<5

Na<10

F<5

#### STORAGE AND HANDLING

**Shipping** Recommended temperature is -40°C, RT

TBD

Storage Store at -40°C for up to 1 year

**Safety** Refer to MSDS for safe handling practices.

All values are considered typical based on tests believed to be accurate. Polysciences, Inc. may change the data as appropriate.

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